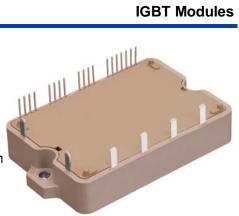


IGBT Modules

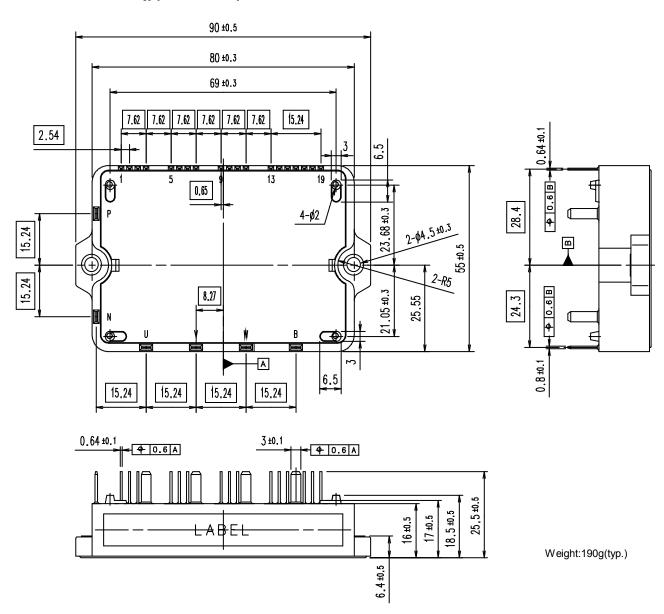
IGBT Module (V series) 600V / 50A / IPM

■ Features

- Temperature protection provided by directly detecting the junction temperature of the IGBTs
- ·Low power loss and soft switching
- ·High performance and high reliability IGBT with overheating protection
- ·Higher reliability because of a big decrease in number of parts in built-in control circuit



■ Outline drawing (Unit: mm)



IGBT Modules

■ Absolute Maximum Ratings

Tc=25°C, Vcc=15V unless otherwise specified.

	Items					Units
Co	llector-Emitter Voltage *1		VCES	0	600	V
Sh	Short Circuit Voltage		Vsc	200	400	V
Inverter		DC	Ic	1	50	Α
ΙË	Collector Current	1ms	ICP	-	100	Α
۱¥		Duty=100% *2	-lc	1	50	Α
_=	Collector Power Dissipation	1 device *3	Pc	-	290	W
Brake	Collector Current	DC	Ic	1	-	Α
	Collector Current	1ms	ICP	-	-	Α
ΙÄ	Forward Current of Diode		lF	1	_	Α
	Collector Power Dissipation	1 device *3	Pc	-	-	W
Sι	pply Voltage of Pre-Driver *4		Vcc	-0.5	20	V
Inp	out Signal Voltage *5		Vin	-0.5	Vcc+0.5	V
Αla	arm Signal Voltage *6		VALM	-0.5	Vcc	V
Ala	arm Signal Current *7		IALM	-	20	mΑ
	nction Temperature		Tj	-	150	°C
	perating Case Temperature		Topr	-20	110	°C
St	Storage Temperature			-40	125	°C
	lder Temperature *8		Tsol	-	260	°C
Isc	olating Voltage *9		Viso	-	AC2500	Vrms
Sc	rew Torque	Mounting (M4)	-	-	1.7	Nm

Notes

- *1: VCES shall be applied to the input voltage between terminal P-(U,V, W,B) and (U,V, W,B)-N.
- *2: Duty=125°C/Rth(j-c)D/(IF×VF Max.)×100
- *3: PC=125°C/Rth(j-c)Q (Inverter & Brake)
- *4: VCC shall be applied to the input voltage between terminal No.4 and 1, 8 and 5, 12 and 9,14 and 13.
- *5: Vin shall be applied to the input voltage between terminal No.3 and 1, 7 and 5, 11 and 9,15~18 and 13.
- *6: VALM shall be applied to the voltage between terminal No.2 and 1, 6 and 5, 10 and 9,19 and 13.
- *7: IALM shall be applied to the input current to terminal No.2,6,10 and 19.
- *8: Immersion time 10±1sec. 1time
- *9: Terminal to base, 50/60Hz sine wave 1min. All terminals should be connected together during the test.

■ Electrical Characteristics (Tj=25°C, VCC=15V unless otherwise specified.)

Main circuit

	Item	Symbol		(Condition	S	Min.	Тур.	Max.	Units
ē	Collector Current at off signal input	ICES	VCE	= 600V			ı	ı	1.0	mA
Inverter	Collector-Emitter	VCE(sat)	Ic	= 50A		Terminal	-	-	1.85	V
l §	saturation voltage	V CL(Sat)				Chip	-	1.25	-	V
<u>=</u>	Forward voltage of FWD	VF	lF	= 50A		Terminal	-	ì	2.1	V
	I of ward voltage of 1 vvD	V٢	F		Chip	-	1.6	-	V	
4)	Collector Current at off signal input	ICES	VCE	=			ı	ı	ı	mA
Brake	Collector-Emitter	VCE(sat)	Ic	=		Terminal	-	1	-	V
	saturation voltage	V C⊏(Sat)				Chip	-	ì	-	V
1 "	Forward voltage of FWD	VF	lF	=		Terminal	-	1	-	V
	I of ward voltage of 1 vvD	V٢				Chip	-	ì	-	V
		ton	VDC	= 300V	, Tj=12	5°C	1.1	1	-	μs
Switching time		toff	Ic	= 50A			-	-	2.1	μs
		trr	VDC	= 300V			-	-	0.3	μs
		ui	lF	= 50A						



IGBT Modules

Control circuit

Item	Symbol	Conditions	S	Min.	Тур.	Max.	Units
Supply current of P-side pre-driver (per one unit)	Ісср	Switching Frequency = 0-15kHz Tc=-20~110°C		1	1	12	mA
Supply current of N-side pre-driver	Iccn			1	1	36	mA
Input signal threshold voltage	Vinth(on)	Vin-GND	ON	1.2	1.4	1.6	V
Imput signal tilleshold voltage	Vinth(off)	VIII-GIND	OFF	1.5	1.7	1.9	V

Protection Circuit

Item	Symbol		Conditions	Min.	Тур.	Max.	Units
Over Current Inverter	loc	Tj=125°C		100	-	-	Α
Protection Level Brake	100	1j=125 C	Resistance Load	-	-	-	Α
Over Current Protection Delay time	tdOC	Tj=125°C		-	5	ı	μs
Short Circuit Protection Delay time	tsc	Tj=125°C		-	2	3	μs
IGBT Chips Over Heating	Тјон	Surface of		150	-	1	Ωຶ
Protection Temperature Level	ПОП	IGBT Chips					
Over Heating Protection Hysteresis	TjH			-	20	-	S
Under Voltage Protection Level	Vuv			11.0	-	12.5	V
Under Voltage Protection Hysteres	Vн			0.2	0.5	-	>
	tALM(OC)	ALM-GND Tc=-20~110		1.0	2.0	2.4	ms
Alarm Signal Hold Time	tALM(UV)	To= 20 - 11	o°c Vcc≧10V	2.5	4.0	4.9	ms
	talm(TjOH)	1020~110	U C —	5.0	8.0	11.0	ms
Resistance for current limit	RALM			960	1265	1570	Ω

■ Thermal Characteristics (Tc = 25°C)

Item			Symbol	Min.	Тур.	Max.	Units
	Inverter	IGBT	Rth(j-c)Q	1	-	0.43	°C/W
Junction to Case	IIIVEITEI	FWD	Rth(j-c)D	ı	-	0.69	%C/W
Thermal Resistance*10	Brake	IGBT	Rth(j-c)Q	1	-	ı	°C/W
	Diake	FWD	Rth(j-c)D	-	-	-	°C/W
Case to Fin Thermal Resistance with Compound			Rth(c-f)	-	0.05	-	°C/W

^{*10:} For 1device, the measurement point of the case is just under the chip.

■ Noise Immunity (VDC=300V, VCC=15V)

Item	Conditions	Min.	Тур.	Max.	Units
Common mode	Pulse width 1µs,polarity ±,10min.	±2.0	-	-	kV
rectangular noise	Judge: no over-current, no miss operating				

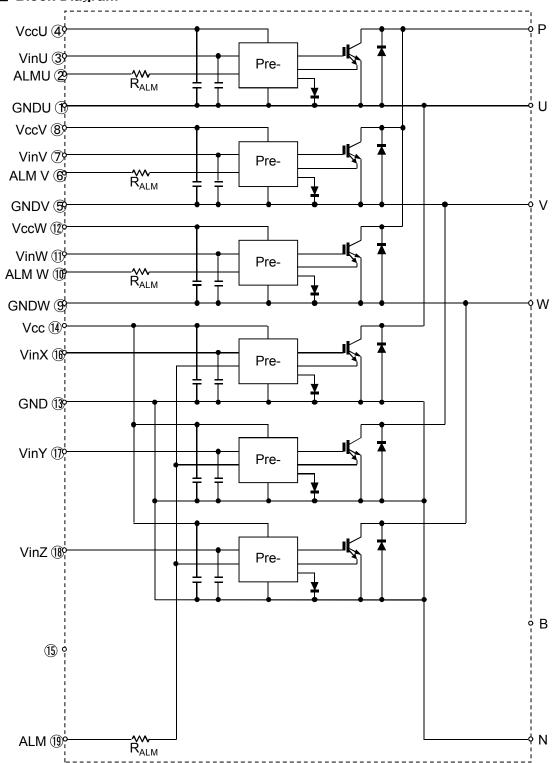
■ Recommended Operating Conditions

Item	Symbol	Min.	Тур.	Max.	Units
DC Bus Voltage	VDC	1	-	400	V
Power Supply Voltage of Pre-Driver	Vcc	13.5	15.0	16.5	V
Switching frequency of IPM	fsw	1	-	20	kHz
Arm shoot through blocking time for IPM's input signal	tdead	1.0	-	1	μs
Screw Torque (M4)	-	1.3	-	1.7	Nm



IGBT Modules

■ Block Diagram



Pre-drivers include following functions

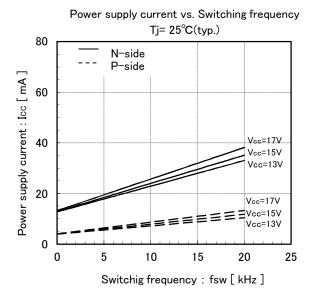
- 1. Amplifier for driver
- 2. Short circuit protection
- 3. Under voltage lockout circuit
- 4. Over current protection
- 5. IGBT chip over heating protection



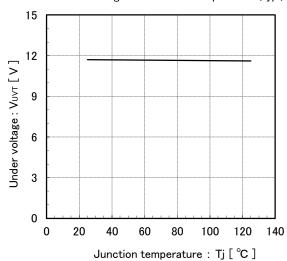
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■ Characteristics (Representative)

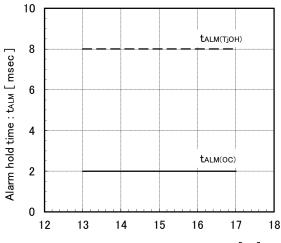
Control Circuit



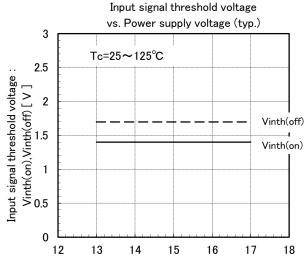
Under voltage vs. Junction temperature (typ.)



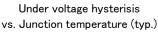
Alarm hold time vs. Power supply voltage (typ.)

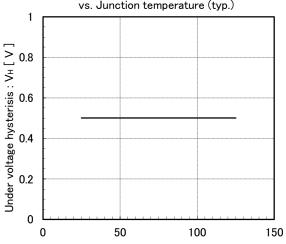


Power supply voltage: VCC [V]

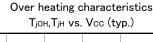


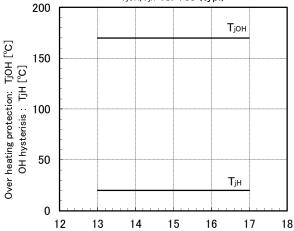
Power supply voltage: VCC [V]





Junction temperature : Tj [°C]

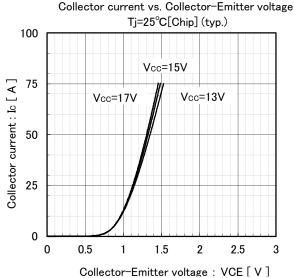




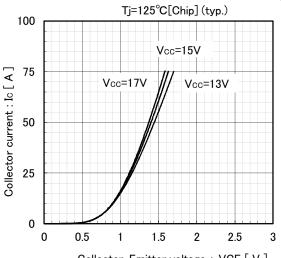
Power supply voltage: VCC [V]

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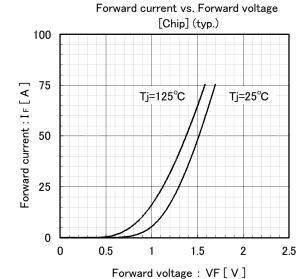
Inverter



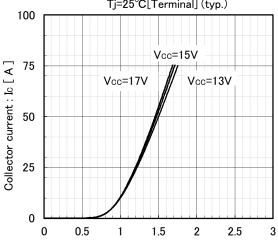
Collector current vs. Collector-Emitter voltage



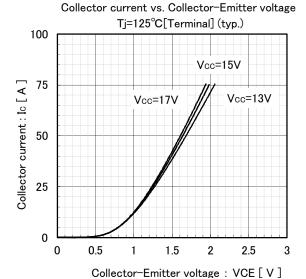
Collector-Emitter voltage: VCE [V]



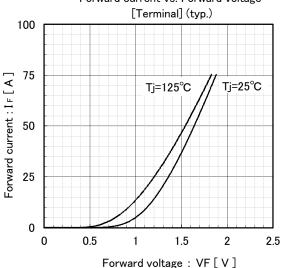
Collector current vs. Collector-Emitter voltage Tj=25°C[Terminal] (typ.)



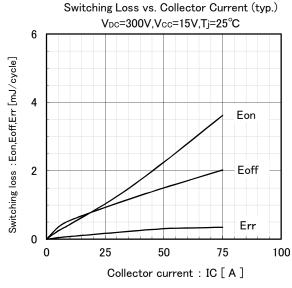
Collector-Emitter voltage: VCE [V]

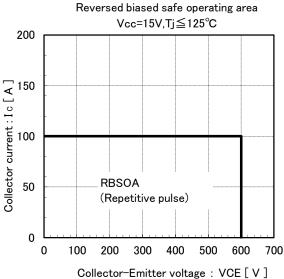


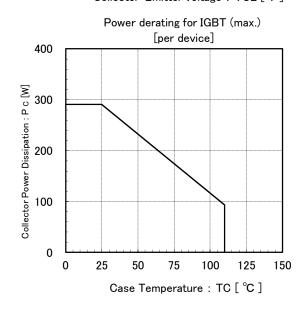
Forward current vs. Forward voltage

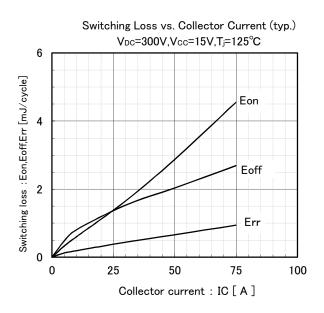


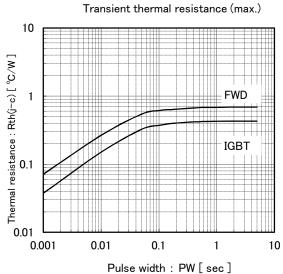
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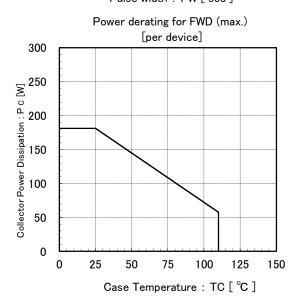






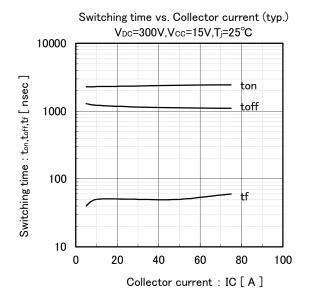


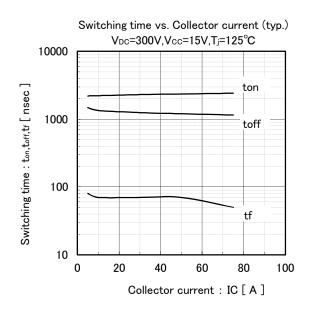


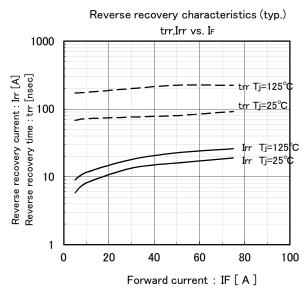


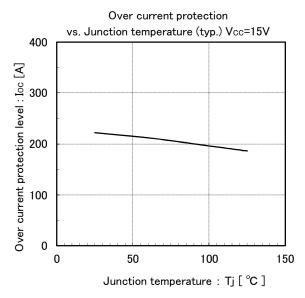


IGBT Modules











IGBT Modules

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